



Product Change Notification: ALAN-05MUPB051

Date:

02-Sep-2024

Product Category:

16-Bit - Microcontrollers And Digital Signal Controllers, 8-Bit Microcontrollers

Notification Subject:

CCB 6850 Final Notice: Qualification of 4900F as new die-attach material and G631H as new mold compound material for selected dsPIC33FJ128xx, dsPIC33FJ256xx, dsPIC33FJ32Gxx, dsPIC33FJ64xx, MTR1202xx, PIC18F9xx, PIC24FJ128Gxx, PIC24FJ192Gxx, PIC24FJ256Gxx, PIC24FJ64Gxx, PIC24FJ96Gxx, PIC24HJ128GPxx, PIC24HJ256GPxx, and PIC24HJ64GPxx device families available in 100L TQFP (12x12x1mm) package.

Affected CPNs:

[ALAN-05MUPB051_Affected_CPN_09022024.pdf](#)

[ALAN-05MUPB051_Affected_CPN_09022024.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of 4900F as new die-attach material and G631H as new mold compound material for selected dsPIC33FJ128xx, dsPIC33FJ256xx, dsPIC33FJ32Gxx, dsPIC33FJ64xx, MTR1202xx, PIC18F9xx, PIC24FJ128Gxx, PIC24FJ192Gxx, PIC24FJ256Gxx, PIC24FJ64Gxx, PIC24FJ96Gxx, PIC24HJ128GPxx, PIC24HJ256GPxx, and PIC24HJ64GPxx device families available in 100L TQFP (12x12x1mm) package.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)
Wire Material	Au	Au
Die Attach Material	2288A	4900F
Molding Compound Material	9200THF	G631H
Lead-Frame Material	C7025	C7025
DAP Surface Prep	Ring plating	Double Ring plating

Impacts to Data Sheet:None

Change ImpactNone

Reason for Change:To improve manufacturability by qualifying 4900F as new die-attach material and G631H as new mold compound material.

Change Implementation Status:In Progress

Estimated First Ship Date:September 17, 2024 (date code: 2438)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	March 2024					>	September 2024				
Workweek	09	10	11	12	13		36	37	38	39	40
Initial PCN Issue Date		X									
Qual Report Availability							X				
Final PCN Issue Date							X				

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as

PCN_#_Qual_Report.

Revision History: March 07, 2024: Issued initial notification.

September 02, 2024: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on September 17, 2024.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ALAN-05MUPB051_Pre and Post Change_Summary.pdf
PCN_ALAN-05MUPB051_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

- PIC18F97J60-I/PT
- PIC18F97J60T-I/PT
- PIC18F96J60-I/PT
- PIC24FJ256GB110-I/PTREL
- PIC24FJ256GB110T-I/PT
- PIC24FJ64GB110-I/PT
- PIC24FJ128GB110-I/PT
- PIC24FJ256GA110T-I/PT
- PIC24FJ192GB110-I/PT
- PIC24HJ64GP510A-I/PT
- PIC24HJ64GP210A-I/PT
- PIC24HJ128GP310AT-I/PT
- PIC24HJ128GP510AT-I/PT
- DSPIC33FJ128MC510A-I/PT
- DSPIC33FJ128MC710A-I/PT
- PIC24HJ64GP210AT-I/PT
- PIC24HJ64GP510AT-I/PT
- DSPIC33FJ128MC510AT-I/PT
- PIC24HJ128GP210A-I/PT
- PIC24HJ128GP310A-I/PT
- PIC24HJ128GP510A-I/PT
- DSPIC33FJ64GP310A-I/PT
- DSPIC33FJ64GP710A-I/PT
- DSPIC33FJ128GP310A-I/PT
- DSPIC33FJ128GP710A-I/PT
- DSPIC33FJ64MC510A-I/PT
- DSPIC33FJ128GP710A-E/PT
- DSPIC33FJ64MC710A-E/PT
- PIC24FJ256GB110-I/PT
- PIC24FJ128GA010-I/PT
- PIC24FJ192GA110-I/PT
- PIC24FJ256GA110-I/PT
- PIC24FJ128GA010T-I/PT
- PIC24FJ256GA110-E/PT
- PIC24FJ96GA010-I/PT
- PIC24FJ64GA010-I/PT
- PIC24FJ128GA110-E/PT
- PIC24FJ128GA110-I/PT
- DSPIC33FJ64GP710AT-I/PT
- DSPIC33FJ128GP310AT-I/PT
- DSPIC33FJ128GP710AT-I/PT
- PIC24HJ128GP510A-I/PT042
- PIC24HJ128GP510A-E/PT
- PIC24HJ64GP210A-E/PT
- PIC24HJ64GP510A-E/PT
- DSPIC33FJ128GP310A-E/PT

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PIC24HJ256GP210A-E/PT
DSPIC33FJ128MC510-I/PTC22
PIC24HJ256GP610A-E/PT
DSPIC33FJ128MC510A-I/PTC31
PIC24HJ256GP610T-I/PT
DSPIC33FJ256GP710T-I/PT
PIC24HJ256GP610AT-I/PT
DSPIC33FJ256GP710AT-I/PT
DSPIC33FJ256MC510AT-I/PT
DSPIC33FJ256GP710A-E/PT
DSPIC33FJ256MC510A-E/PT
DSPIC33FJ256MC710A-E/PT
PIC24HJ256GP210A-I/PT
DSPIC33FJ256MC710AT-I/PT
DSPIC33FJ256MC710A-I/PT
PIC24HJ64GP210-I/PT
PIC24HJ64GP510-I/PT
PIC24HJ128GP210-I/PT
PIC24HJ128GP310-I/PT
DSPIC33FJ32GS610-50I/PT
PIC24HJ256GP610A-I/PT
DSPIC33FJ256GP510A-I/PT
DSPIC33FJ256GP710A-I/PT
DSPIC33FJ256MC510A-I/PT
DSPIC33FJ64GS610-50I/PT
PIC24HJ128GP510-I/PT
PIC24HJ256GP210-I/PT
DSPIC33FJ256MC510T-I/PT
DSPIC33FJ256MC710T-I/PT
DSPIC33FJ256GP710AT-E/PT
DSPIC33FJ256MC710AT-E/PT
PIC24HJ64GP510T-I/PT
PIC24HJ256GP210T-I/PT
DSPIC33FJ32GS610-E/PT
DSPIC33FJ64GS610-E/PT
DSPIC33FJ128GP710-I/PT
DSPIC33FJ256GP510-I/PT
DSPIC33FJ64GP710-I/PT
PIC24HJ256GP610-I/PT
DSPIC33FJ64GP310-I/PT
DSPIC33FJ128MC510-I/PT
DSPIC33FJ128MC710-I/PT
DSPIC33FJ256MC510-I/PT
DSPIC33FJ256MC710-I/PT
DSPIC33FJ128GP310-I/PT
DSPIC33FJ256GP710-I/PT
DSPIC33FJ64MC510-I/PT
DSPIC33FJ64GS610-I/PT

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- DSPIC33FJ64MC710-I/PT
- PIC24FJ64GA010T-I/PT
- DSPIC33FJ256GP710T-I/PTB21
- DSPIC33FJ128MC510AT-I/PTC30
- PIC24HJ256GP610A-H/PT
- DSPIC33FJ256GP710A-H/PT
- DSPIC33FJ256MC710A-H/PT